#### **(Note 1) ABSOLUTE MAXIMUM RATINGS**



IVPCA/B .. 10mA Operating Temperature Range (Note 2) .. –40°C to 85°C Storage Temperature Range ................ –65°C to 150°C Maximum Junction Temperature ................................ 125°C Lead Temperature (Soldering, 10 sec)................ 300°C

# **PACKAGE/ORDER INFORMATION**



Consult LTC Marketing for parts specified with wider operating temperature ranges.

# **ELECTRICAL CHARACTERISTICS** The  $\bullet$  denotes specifications which apply over the full operating

**temperature range, otherwise specifications are at TA = 25**°**C. VIN = 3.6V, SHDN = VIN unless otherwise noted.**





#### **ELECTRICAL CHARACTERISTICS** The  $\bullet$  denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ \text{C}$ . V<sub>IN</sub> = 3.6V,  $\overline{SHDN} = V_{1N}$ , unless otherwise noted.



**Note 1:** Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

**Note 2:** Specifications are assured over the –40°C to 85°C temperature range by design characterization and correlation with statistical process controls.

**Note 3:** Slew rate is measured open loop. The rise time at V<sub>PCA</sub> or V<sub>PCB</sub> is measured between 1V and 2V.

**Note 4:** Includes maximum DAC offset voltage and maximum control voltage.

**Note 5:** This is the time from SHDN rising edge 50% switch point to  $V_{\text{PCA/B}} = 250 \text{mV}$ .

**Note 6:** Guaranteed by design. This parameter is not production tested. **Note 7:** Bandwidth is calculated using the 10% to 90% rise time:  $BW = 0.35/rise time$ 

## **TYPICAL PERFORMANCE CHARACTERISTICS**



## **PIN FUNCTIONS** (LTC4402-1/LTC4402-2)

**V<sub>IN</sub>** (Pin 1): Input Supply Voltage, 2.7V to 6V. V<sub>IN</sub> should be bypassed with 0.1µF and 100pF ceramic capacitors.

**VPCA (Pin 2):** Power Control Voltage Output. This pin drives an external RF power amplifier power control pin. The maximum load capacitance is 100pF. The output is capable of rail-to-rail swings at low load currents. Selected when BSEL is low.

**VPCB (Pin 3): (LTC4402-2 Only)** Power Control Voltage Output. This pin drives an external RF power amplifier power control pin. The maximum load capacitance is 100pF. The output is capable of rail-to-rail swings at low load currents. Selected when BSEL is high.

**GND (Pin 3/4):** System Ground.



## **PIN FUNCTIONS** (LTC4402-1/LTC4402-2)

**GND (Pin 4/5):** System Ground.

**PCTL (Pin 5/6):** Analog Input. The external power control DAC drives this input. The amplifier servos the RF power until the RF detected signal equals the DAC signal applied at this pin.

**SHDN (Pin 6/7):** Shutdown Input. A logic low on the SHDN pin places the part in shutdown mode. A logic high enables the part after 10µs. SHDN has an internal 150k pull-down resistor to ensure that the part is in shutdown when no input is applied.

**VHOLD (Pin 7/8):** Asserted high prior to AM modulation, opens control loop and holds voltage at  $V_{PCA}$  or  $V_{PCB}$  during EDGE modulation.

**BSEL (Pin 9): (LTC4402-2 Only)** Selects V<sub>PCA</sub> when low and  $V_{PCB}$  when high. This input has an internal 150k resistor to ground.

**RF (Pin 8/10):** Coupled RF Feedback Voltage . This input is referenced to  $V_{IN}$ . The frequency range is 300MHz to 2400MHz. This pin has an internal  $250\Omega$  termination, an internal Schottky diode detector and peak detector capacitor.



## **APPLICATIONS INFORMATION U W U U**

#### **Operation**

The LTC4402-1/-2 single/dual band RF power controller integrates several functions to provide RF power control over frequencies ranging from 300MHz to 2.4GHz. These functions include an internally compensated amplifier to control the RF output power, an autozero section to cancel internal and external voltage offsets, an RF Schottky diode peak detector and amplifier to convert the RF feedback signal to DC, a multiplexer to switch the controller output to either  $V_{PCA}$  or  $V_{PCB}$ , a  $V_{PCA/B}$  overvoltage clamp, compression and a bandgap reference.

#### **Band Selection**

The LTC4402-2 is designed for multiband operation. The BSEL pin will select output  $V_{PCA}$  when low and output  $V_{PCB}$  when high. For example,  $V_{PCA}$  could be used to drive an 850MHz/900MHz channel and  $V_{PCB}$  a 1.8GHz/1.9GHz channel. BSEL must be established before the part is enabled. The LTC4402-1 can be used to drive a single RF channel or dual channel with integral multiplexer.

### **Control Amplifier**

The control amplifier supplies the power control voltage to the RF power amplifier. A portion (typically –19dB for low frequencies and –14dB for high frequencies) of the RF output voltage is coupled into the RF pin, to close the gain control loop. When a DAC voltage is applied to PCTL, the amplifier quickly servos  $V_{PCA}$  or  $V_{PCR}$  positive until the detected feedback voltage applied to the RF pin matches the voltage at PCTL. This feedback loop provides accurate RF power control.  $V_{PCA}$  or  $V_{PCR}$  are capable of driving a 6mA load current and 100pF load capacitor.

### **RF Detector**

The internal RF Schottky diode peak detector and amplifier convert the coupled RF feedback voltage to a low frequency voltage. This voltage is compared to the DAC voltage at the PCTL pin by the control amplifier to close the RF power control loop. The RF pin input resistance is typically 250 $\Omega$  and the frequency range of this pin is 300MHz to 2400MHz. The detector demonstrates excellent efficiency and linearity over a wide range of input power. The Schottky detector is biased at about 60µA and drives an on-chip peak detector capacitor of 28pF.

#### **Autozero**

An autozero system is included to improve power programming accuracy over temperature. This section cancels internal offsets associated with the Schottky diode detector and control amplifier. External offsets associated with the DAC driving the PCTL pin are also cancelled. Offset drift due to temperature is cancelled between each burst. The maximum offset allowed at the DAC output is limited to 400mV. Autozeroing is performed after SHDN is asserted high. An internal delay of typically 9µs enables the  $V_{PCA/B}$  output after the autozero has settled. When the part is enabled, the autozero capacitors are held and the V<sub>PCA</sub> or V<sub>PCB</sub> pin is connected to the buffer amplifier output. The hold droop voltage of typically  $\langle 1 \mu V/ms \rangle$ provides for accurate offset cancellation.

### **Filter**

There is a 270kHz filter included in the PCTL path. This filter is trimmed at test.

### **Modes of Operation**

**Shutdown:** The part is in shutdown mode when SHDN is low.  $V_{PCA}$  and  $V_{PCB}$  are held at ground and the power supply current is typically 10 $\mu$ A.

**Enable:** When SHDN is asserted high the part will automatically calibrate out all offsets. This takes about 9µs and is controlled by an internal delay circuit. After  $9\mu s$  V<sub>PCA</sub> or  $V_{PCB}$  will step up to the starting voltage of 450mV. The user can then apply the ramp signal. The user should wait at least 11µs after SHDN has been asserted high before applying the ramp. The DAC should be settled 2µs after asserting SHDN high.

**Hold:** When the V<sub>HOLD</sub> pin is low, the RF power control feedback loop is closed and the LTC4402-X servos the  $V_{\text{PCA}}/V_{\text{PCB}}$  pins according to the voltages at the PCTL and RF inputs. When the  $V_{HOLD}$  pin is asserted high, the RF power control feedback loop is opened and the power control voltage at  $V_{PCA}$  or  $V_{CPB}$  is held at its present level. Generally, the  $V_{HOLD}$  pin is asserted high after the power up ramp has been completed and the desired RF output power has been achieved. The power control voltage is then held at a constant voltage during the EDGE modulation time. After the EDGE modulation is completed and prior to power ramping down, the  $V_{HOLD}$  pin is set low.



# **APPLICATIONS INFORMATION U W U U**

This closes the RF power control loop and the RF power is then controlled during ramp down.

## **LTC4402-1 Description**

The LTC4402-1 is identical in performance to the LTC4402-2 except that only one control output  $(V_{PCA})$  is available. The LTC4402-1 can drive a single band (300MHz to 2400MHz) or a dual RF channel module with an internal multiplexer. Several manufacturers offer dual RF channel modules with an internal multiplexer.

## **General Layout Considerations**

The LTC4402-X should be placed near the coupling components. The feedback signal line to the RF pin should be a 50Ω transmission line.

## **Capacitive Coupling**

An alternative to a directional coupler is illustrated on the first page of this data sheet. This method couples RF from the power amplifier to the power controller through a 0.4pF  $\pm$ 0.05pF capacitor and 50 $\Omega$  series resistor, completely eliminating the directional coupler.



T1: PART COMES OUT OF SHUTDOWN 11µs PRIOR TO BURST.

T2: INTERNAL TIMER COMPLETES AUTOZERO CORRECTION, TYPICALLY 9µs.

T3: BASEBAND CONTROLLER STARTS RF POWER RAMP UP AT LEAST 11µs AFTER SHDN IS ASSERTED HIGH.

T4: BASEBAND CONTROLLER COMPLETES RAMP UP.

- T5: CONTROL LOOP OPENS, VPCA/B VOLTAGE HELD, AM MODULATION STARTS.
- T6: AM MODULATION STOPS, CONTROL LOOP CLOSES, V<sub>PCA/B</sub> WILL FOLLOW DAC.<br>T7: BASEBAND CONTROLLER STARTS RF POWER RAMP DOWN AT END OF BURST.
- 

T8: RETURNS TO SHUTDOWN MODE BETWEEN BURSTS.

Application Note AN91 describes the capacitive coupling scheme in full detail. Demo boards featuring this coupling method are available upon request.

### **Power Ramp Profiles**

The external voltage gain associated with the RF channel can vary significantly between RF power amplifier types. Frequency compensation generally defines the loop dynamics that impact the power/time response and possibly (slow loops) the power ramp sidebands. The LTC4402-X operates open loop until an RF voltage appears at the RF pin, at which time the loop closes and the output power follows the DAC profile. The RF power amplifier will require a certain control voltage level (threshold) before an RF output signal is produced. The LTC4402-X  $V_{PCA/B}$ outputs must quickly rise to this threshold voltage in order to meet the power/time profile. To reduce this time, the LTC4402-X starts at 450mV. However, at very low power levels the PCTL input signal is small, and the  $V_{PCA/B}$ outputs may take several microseconds to reach the RF power amplifier threshold voltage. To reduce this time, it may be necessary to apply a positive pulse at the start of the ramp to quickly bring the  $V_{PCA/B}$  outputs to the threshold voltage. This can generally be achieved with DAC programming. The magnitude of the pulse is dependent on the RF amplifier characteristics.

Power ramp sidebands and power/time are also a factor when ramping to zero power. For RF amplifiers requiring high control voltages, it may be necessary to further adjust the DAC ramp profile. When the power is ramped down, the loop will eventually open at power levels below the LTC4402-X detector threshold. The LTC4402-X will then go open loop and the output voltage at  $V_{PCA}$  or  $V_{PCB}$  will stop falling. If this voltage is high enough to produce RF output power, the power/time or power ramp sidebands may not meet specification. This problem can be avoided by starting the DAC ramp from 200mV (Figure 1). At the end of the cycle, the DAC can be ramped down to 0mV. This applies a negative signal to the LTC4402-X thereby ensuring that the  $V_{PCA/B}$  outputs will ramp to OV. The 200mV ramp step must be applied at least 2µs after SHDN is asserted high to allow the autozero to cancel the step.









#### **Demo Board**

The LTC4402-X demo board is available upon request. The demo board has a 900MHz and an 1800MHz RF channel and  $V_{H01D}$  controlled by the LTC4402-X. Timing signals for SHDN are generated on the board using a 13MHz crystal oscillator reference. The PCTL power control pin is driven by a 10-bit DAC and the DAC profile can be loaded via a serial port. The serial port data is stored in a flash memory which is capable of storing eight ramp profiles. The board is supplied preloaded with four GSM power profiles and four DCS power profiles covering the entire power range. External timing signals can be used in place of the internal crystal controlled timing. A power ramp software package is available which allows the user to create power control ramps.

### **LTC4402 Control Loop Stability**

There are several factors that can improve or degrade loop frequency stability.

1) The additional voltage gain supplied by the RF power amplifier increases the loop gain, raising poles normally below the 0dB axis. The extra voltage gain can vary significantly over input/output power ranges, frequency, power supply, temperature and manufacturer. RF power amplifier gain control transfer functions are often not available and must be generated by the user. Loop oscillations are most likely to occur in the midpower range where the external voltage gain associated with the RF power amplifier typically peaks. It is useful to measure the oscillation or ringing frequency to determine whether it corresponds to the expected loop bandwidth and thus is due to high gain bandwidth.

2) Loop voltage losses supplied by the coupler network will improve phase margin. The larger the coupler loss the more stable the loop will become. However, larger losses reduce the RF signal to the LTC4402-X and detector performance may be degraded at low power levels. (See RF Detector Characteristics.)

3) Additional poles within the loop due to filtering or the turn-on response of the RF power amplifier can degrade the phase margin if these pole frequencies are near the effective loop bandwidth frequency. Generally loops using RF power amplifiers with fast turn-on times have more phase margin. Extra filtering below 16MHz should never be placed within the control loop, as this will only degrade phase margin.

4) Control loop instability can also be due to open loop issues. RF power amplifiers should first be characterized in an open loop configuration to ensure self oscillation is not present. Self-oscillation is often related to poor power supply decoupling, ground loops, coupling due to poor layout and extreme  $V_{SWR}$  conditions. The oscillation frequency is generally in the 100kHz to 10MHz range. Power supply related oscillation suppression requires large value ceramic decoupling capacitors placed close to the RF power amp supply pins. The range of decoupling capacitor values is typically 1nF to 3.3µF.

5) Poor layout techniques associated with the coupler network may result in high frequency signals bypassing the coupler. This could result in stability problems due to the reduction in the coupler loss.



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# **APPLICATIONS INFORMATION**

### **Determining External Loop Gain and Bandwidth**

The external loop voltage gain contributed by the RF channel and coupler network should be measured in a closed loop configuration. A voltage step is applied to PCTL and the change in  $V_{PCA}$  (or  $V_{PCB}$ ) is measured. The detected RF voltage is 0.6 • PCTL and the external voltage gain contributed by the RF power amplifier and coupler network is  $0.6 \cdot \Delta V_{PCTI}/\Delta V_{VPCA}$ . Measuring voltage gain in the closed loop configuration accounts for the nonlinear detector gain that is dependent on RF input voltage and frequency.

The LTC4402-X unity gain bandwidth specified in the data sheet assumes that the net voltage gain contributed by the RF power amplifier and coupler network is unity. The bandwidth is calculated by measuring the rise time between 10% and 90% of the voltage change at  $V_{PCA}$  or  $V_{PCB}$ for a small step in voltage applied to PCTL.

 $BW1 = 0.35/rise time$ 

The LTC4402-X control amplifier unity gain bandwidth (BW1) is typically 450kHz. For PCTL <80mV the phase margin of the control amplifier is typically 90°.

For PCTL voltages <80mV, the RF detected voltage is 0.6PCTL. For PCTL voltages >160mV, RF detected voltage is 1.22PCTL – 0.1. This change in gain is due to an internal compression circuit designed to extend the detector range.

For example, to determine the external RF channel loop voltage gain with the loop closed, apply a 100mV step to PCTL from 0mV to 100mV.  $V_{PCA}$  (or  $V_{PCR}$ ) will increase to supply enough feedback voltage to the RF pin to cancel this 100mV step which would be the required detected voltage of 60mV. Suppose that  $V_{PCA}$  changed from 1.498V to 1.528V to create the RF output power change required. The net external voltage gain contributed by the RF power amplifier and directional coupler network can be calculated by dividing the 60mV change at the RF pin by the 30mV change at the  $V_{PCA}$  pin. The net external voltage gain would then be approximately 2. The loop bandwidth extends to 2 • BW1. If BW1 is 450kHz, the loop bandwidth increases to approximately 0.9MHz. The phase margin can be determined from Figures 2 and 3. Repeat the above voltage gain measurement over the full power and frequency range.

External pole frequencies within the loop will further reduce phase margin. The phase margin degradation, due to external and internal pole combinations, is difficult to determine since complex poles are present. Gain peaking may occur, resulting in higher bandwidth and lower phase margin than predicted from the open loop Bode plot. A low frequency AC SPICE model of the LTC4402-X power controller is included (Figures 6 and 7) to better determine pole and zero interactions. The user can apply external gains and poles to determine bandwidth and phase margin. DC, transient and RF information cannot be extracted from this model. The model is suitable for external gain evaluations up to  $6\times$ . The 270 kHz PCTL input filter limits the bandwidth; therefore, use the RF input as demonstrated in the model.









## **APPLICATIONS INFORMATION**



**Figure 4. Closed Loop Block Diagram**



**Figure 5. SPICE Model Open Loop Gain and Phase Characteristics from RF to V<sub>PCA</sub>, PCTL <80mV** 

This model (Figure 6) is being supplied to LTC users as an aid to low frequency AC circuit design, but its use is not suggested as a replacement for breadboarding. Simulation should be used as a supplement to traditional lab testing.

Users should note very carefully the following factors regarding this model: Model performance in general will

reflect typical baseline specs for a given device, and certain aspects of performance may not be modeled fully. While reasonable care has been taken in the preparation, LTC is not responsible for their correct application. These models are supplied "as is", with no direct or implied responsibility on the part of LTC for their operation within a customer circuit or system. Further, Linear Technology Corporation reserves the right to change these models without prior notice.

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# **APPLICATIONS INFORMATION**

\*LTC4402-X Low Frequency AC Spice Model\* \*Main Network Description GGIN1 ND3 0 ND2 IFB 86E-6 GGXFB IFB 0 0 ND12 33E-6 GGX5 ND11 0 0 ND10 1E-6 GGX6 ND12 0 0 ND11 1E-6 GGX1 ND4 0 0 ND3 1E-6 GGX2 ND6 0 0 ND4 1E-6 GGX3 ND7 0 0 ND6 1E-6 GGX4 ND8 0 0 ND7 1E-6 EEX1 ND9 0 0 ND8 2 CCC1 ND3 0 44E-12 CCPCTL2 ND2 0 7E-12 CCPCTL1 ND1 0 13E-12 CCLINT VPCA 0 5E-12 CCLOAD VPCA 0 33E-12 CCFB1 IFB 0 2.4E-12 CCX5 ND11 0 16E-15 CCX6 ND12 0 1.2E-15 CCP ND10 0 28E-12 CCX2 ND6 0 8E-15 CCX3 ND7 0 32E-15 LLX1 ND5 0 80E-3 RR01 ND3 0 20E6 RRFILT ND2 ND1 44E3 RRPCTL1 PCTL ND1 51E3 RRPCTL2 ND1 0 38E3

RR9 VPCA ND9 50 RRLOAD VPCA 0 2K RRFB1 IFB 0 22E3 RRT RF 0 250 RRX5 ND11 0 1E6 RRX6 ND12 0 1E6 RRSD RF ND10 500 RRX1 ND4 ND5 1E6 RRX2 ND6 0 1E6 RRX3 ND7 0 1E6 RRX4 ND8 0 1E6 \*\*Closed loop feedback, comment-out VPCTL, VRF, Adjust EFB gain to reflect external gain, currently set at 3X<sup>\*\*</sup> \*EFB RF 0 VPCA VIN 3 \*VIN VIN 0 DC 0 AC 1 \*VPCTL PCTL 0 DC 0 \*\*Open loop connections, comment-out EFB, VIN and VPCTL\*\*\*\*\*\* VPCTL PCTL 0 DC 0 VRF RF 0 DC 0 AC 1 \*Add AC statement and print statement as required\*\*\* .AC DEC 50 10 1E7 \*for PSPICE only\*\*\*\*\* .OP .PROBE \* .END





**Figure 7. LTC4402 Low Frequency AC Model**



## **TYPICAL APPLICATIONS**

**Single Band Cellular Telephone Transmitter Dual Band Cellular Telephone Transmitter**



**MS8 Package**

## **U PACKAGE DESCRIPTIO**



NOTE: 1. DIMENSIONS IN MILLIMETER/(INCH)

2. DRAWING NOT TO SCALE 3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.152mm (.006") PER SIDE

4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.

INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.152mm (.006") PER SIDE

5. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.102mm (.004") MAX



Information furnished by Linear Technology Corporation is believed to be accurate and reliable. However, no responsibility is assumed for its use. Linear Technology Corporation makes no representation that the interconnection of its circuits as described herein will not infringe on existing patent rights.

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